Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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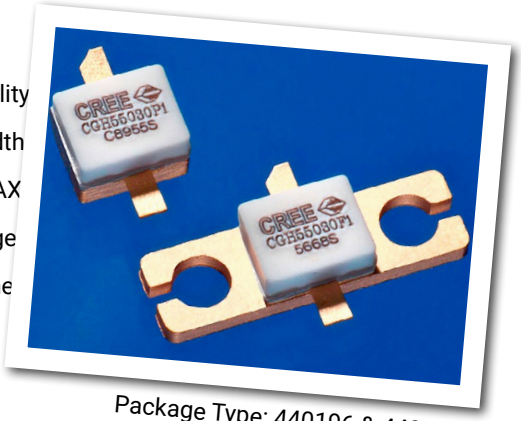
CGH55030F1 / CGH55030P1

30 W, 5500-5800 MHz, 28V, GaN HEMT for WiMAX

Cree's CGH55030F1/CGH55030P1 is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGH55030F1/CGH55030P1 ideal for 5.5-5.8 GHz WiMAX and BWA amplifier applications. The transistor is available in both screw-down, flange and solder-down, pill packages. Based on appropriate external match adjustment, the CGH55030F1/CGH55030P1 is suitable for 4.9 - 5.5 GHz applications as well.



Package Type: 440196 & 440166
PN: CGH55030P1 & CGH55030F1

Typical Performance Over 5.5-5.8GHz (T_c = 25°C) of Demonstration Amplifier

Parameter	5.50 GHz	5.65 GHz	5.80 GHz	Units
Small Signal Gain	9.5	10.0	9.5	dB
EVM at P_{AVE} = 29 dBm	1.1	0.9	0.9	%
EVM at P_{AVE} = 36 dBm	2.2	1.4	1.4	%
Drain Efficiency at P_{AVE} = 4 W	23	24	25	%
Input Return Loss	10.8	22	9.3	dB

Note:
Measured in the CGH55030-AMP amplifier circuit, under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3,
PAR = 9.8 dB @ 0.01 % Probability on CCDF.

Features

RoHS COMPLIANT

- 300 MHz Instantaneous Bandwidth
- 30 W Peak Power Capability
- 10 dB Small Signal Gain
- 4 W P_{AVE} < 2.0 % EVM
- 25 % Efficiency at 4 W Average Power
- Designed for WiMAX Fixed Access 802.16-2004 OFDM Applications
- Designed for Multi-carrier DOCSIS Applications

Large Signal Models Available for ADS and MWO

Absolute Maximum Ratings (not simultaneous) at 25˚C Case Temperature

Parameter	Symbol	Rating	Units	Conditions
Drain-Source Voltage	V_{DSS}	84	Volts	25˚C
Gate-to-Source Voltage	V_{GS}	-10, +2	Volts	25˚C
Power Dissipation	P_{DISS}	14	Watts	
Storage Temperature	T_{STG}	-65, +150	˚C	
Operating Junction Temperature	T_J	225	˚C	
Maximum Forward Gate Current	I_{GMAX}	7.0	mA	25˚C
Maximum Drain Current[1]	I_{DMAX}	3	A	25˚C
Soldering Temperature[2]	T_S	245	˚C	
Screw Torque	τ	60	in-oz	
Thermal Resistance, Junction to Case[3]	$R_{\theta JC}$	4.8	˚C/W	85˚C
Case Operating Temperature[3]	T_C	-40, +150	˚C	30 seconds

Note:
[1] Current limit for long term, reliable operation.
[2] Refer to the Application Note on soldering at www.cree.com/RF/Document-Library
[3] Measured for the CGH55030F1 at P_{DISS} = 14 W

Electrical Characteristics (T_C = 25˚C)

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
DC Characteristics[1]						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.0	–2.3	V_{DC}	V_{DS} = 10 V, I_D = 7.2 mA
Gate Quiescent Voltage	$V_{GS(Q)}$	–	-2.7	–	V_{DC}	V_{DS} = 28 V, I_D = 250 mA
Saturated Drain Current	I_{DS}	5.8	7.0	–	A	V_{DS} = 6.0 V, V_{GS} = 2 V
Drain-Source Breakdown Voltage	V_{BR}	120	–	–	V_{DC}	V_{GS} = -8 V, I_D = 7.2 mA
RF Characteristics[2,3] (T_C = 25˚C, F_0 = 5.65 GHz unless otherwise noted)						
Small Signal Gain	G_{SS}	8.5	10.0	–	dB	V_{DD} = 28 V, I_{DQ} = 250 mA
Drain Efficiency[4]	η	19	24	–	%	V_{DD} = 28 V, I_{DQ} = 250 mA, P_{AVE} = 4 W
Error Vector Magnitude	EVM	–	2.0	2.5	%	V_{DD} = 28 V, I_{DQ} = 250 mA, P_{AVE} = 4 W
Output Mismatch Stress	VSWR	–	–	10 : 1	Ψ	No damage at all phase angles, V_{DD} = 28 V, I_{DQ} = 250 mA, P_{AVE} = 4 W
Dynamic Characteristics						
Input Capacitance	C_{GS}	–	9.0	–	pF	V_{DS} = 28 V, V_{gs} = -8 V, f = 1 MHz
Output Capacitance	C_{DS}	–	2.6	–	pF	V_{DS} = 28 V, V_{gs} = -8 V, f = 1 MHz
Feedback Capacitance	C_{GD}	–	0.4	–	pF	V_{DS} = 28 V, V_{gs} = -8 V, f = 1 MHz

Notes:
[1] Measured on wafer prior to packaging.
[2] Measured in the CGH55030-AMP test fixture.
[3] Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5 ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.
[4] Drain Efficiency = P_{OUT} / P_{DC}.

Cree, Inc.
4600 Silicon Drive
Durham, North Carolina, USA 27703
USA Tel: +1.919.313.5300
Fax: +1.919.869.2733
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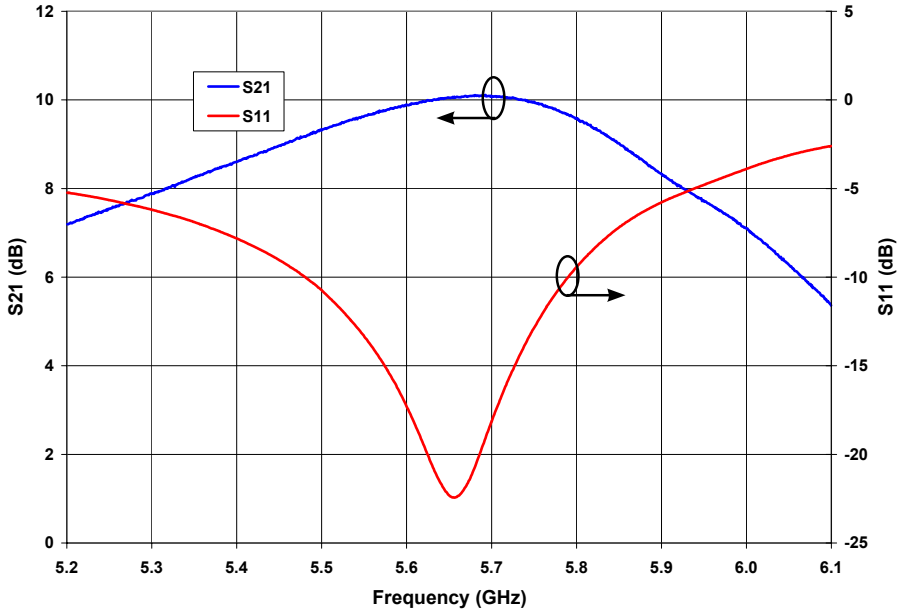
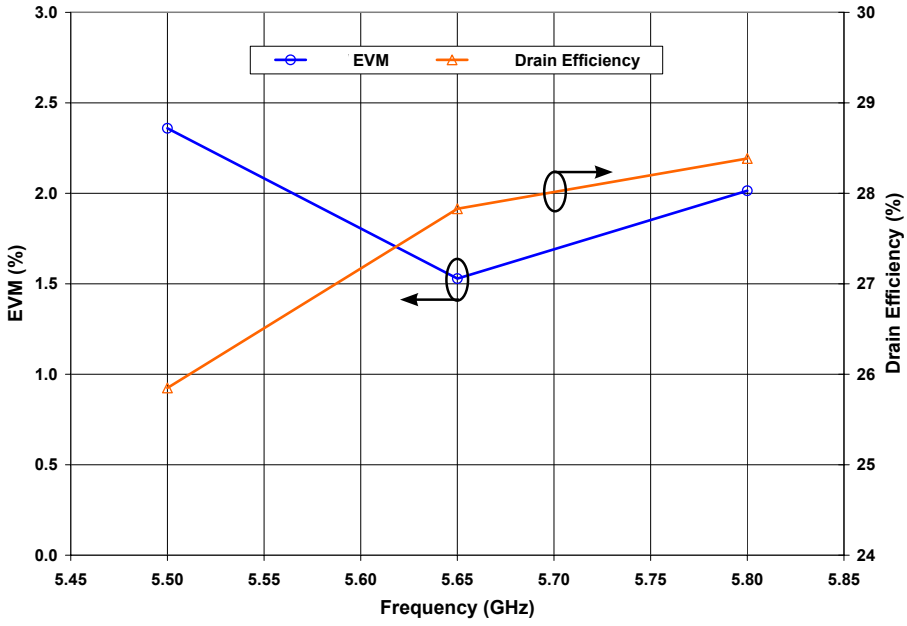
Typical WiMAX Performance

Small Signal S-Parameters vs Frequency of CGH55030F1 and CGH55030P1 in the CGH55030-AMP
V_{DD} = 28 V, I_{DQ} = 250 mA



Typical EVM and Efficiency versus Frequency of CGH55030F1 and CGH55030P1 in the CGH55030-AMP
V_{DD} = 28 V, I_{DQ} = 250 mA, 802.16-2004 OFDM, PAR=9.8 dB, P_{AVE} = 5 W



Note:
Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

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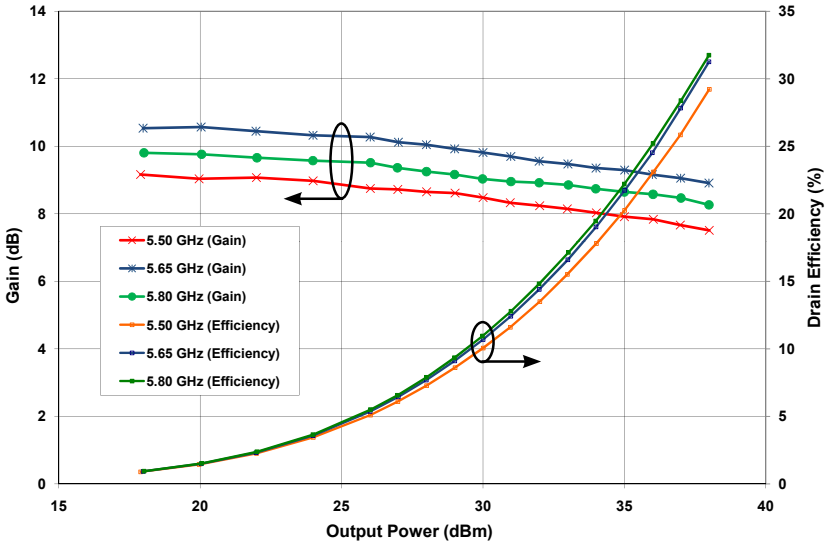
Durham, North Carolina, USA 27703
USA Tel: +1.919.313.5300
Fax: +1.919.869.2733
www.cree.com/rf

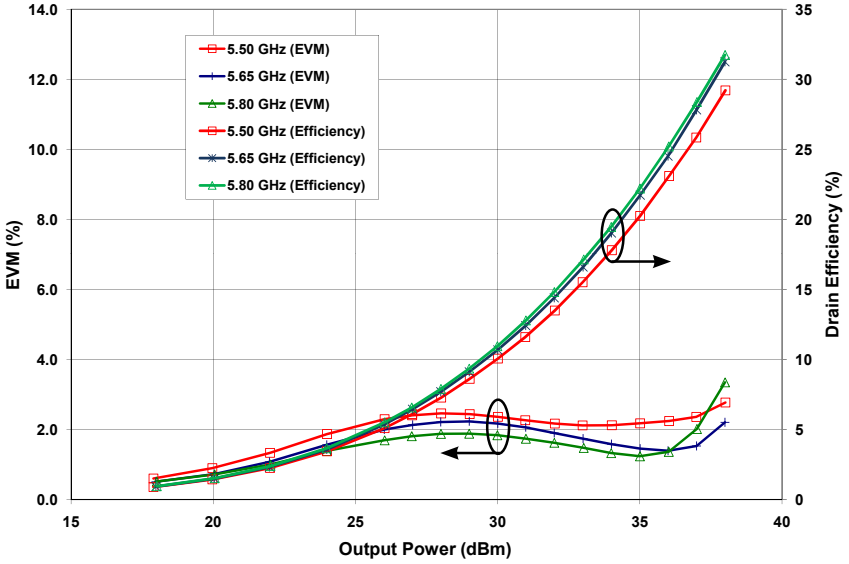
Typical WiMAX Performance

Drain Efficiency and Gain vs Output Power of CGH55030F1 and CGH55030P1 in CGH55030-AMP
V_{DD} = 28 V, I_{DQ} = 250 mA, 802.16-2004 OFDM, PAR=9.8 dB



Note:
Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

Typical EVM and Drain Efficiency vs Output Power of CGH55030F1 and CGH55030P1 in CGH55030-AMP at 5.50GHz, 5.65 GHz, 5.80GHz, 802.16-2004 OFDM, PAR=9.8 dB



Note:
Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

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4600 Silicon Drive
Durham, North Carolina, USA 27703
USA Tel: +1.919.313.5300
Fax: +1.919.869.2733
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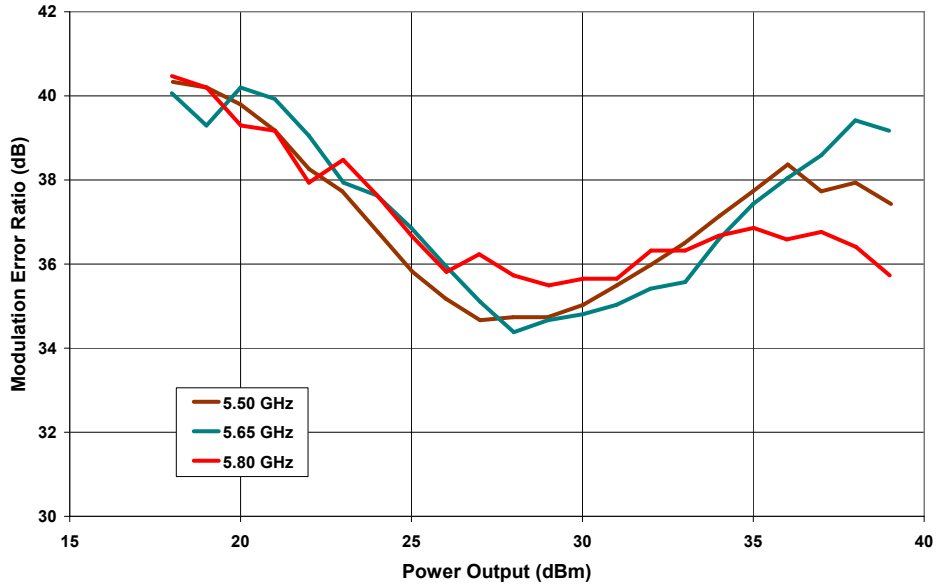
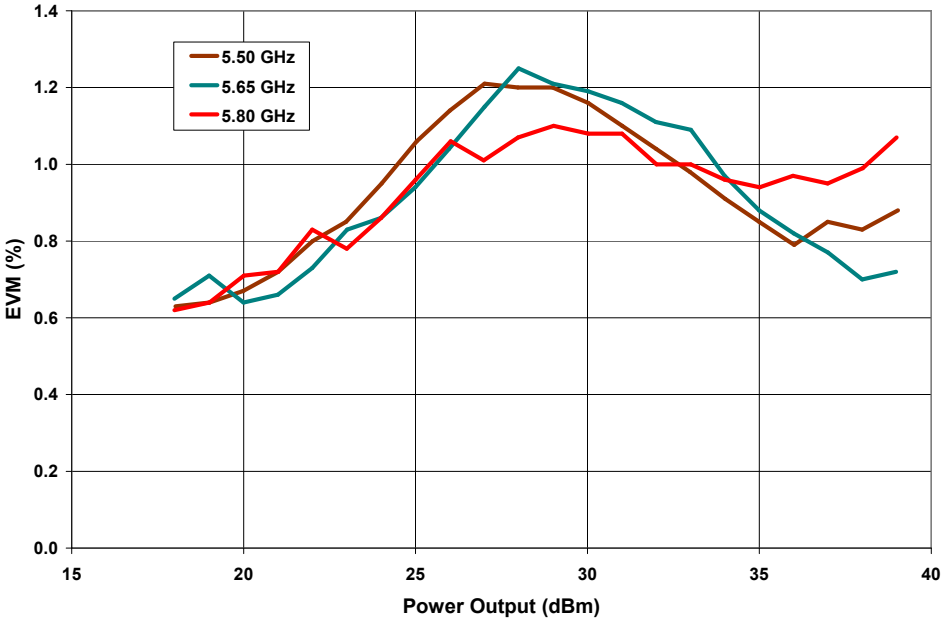
Typical DOCSIS Performance

Modulation Error Ratio vs Output Power of CGH55030F1 and CGH55030P1 in Broadband Amplifier Circuit



Note:
MER is the metric of choice for cable systems and can be related to EVM by the following equation: EVM(%) = 100 x 10 ^ -((MERdB + MTAdB)/20). MTA is the "maximum-to-average constellation power ratio" which varies with the modulation type: MTA = 0 for BPSK and QPSK; 2.55 for 16QAM and 8QAM-DS; 3.68 for 64QAM and 32QAM-DS; 4.23 for 256QAM and 128QAM-DS

EVM vs Output Power of CGH55030F1 and CGH55030P1 in Broadband Amplifier Circuit



Note:
Under DOCSIS, 6.0 MHz Channel BW, 64 QAM, PN23, Filter Alpha 0.18, PAR = 6.7dB.

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Durham, North Carolina, USA 27703
USA Tel: +1.919.313.5300
Fax: +1.919.869.2733
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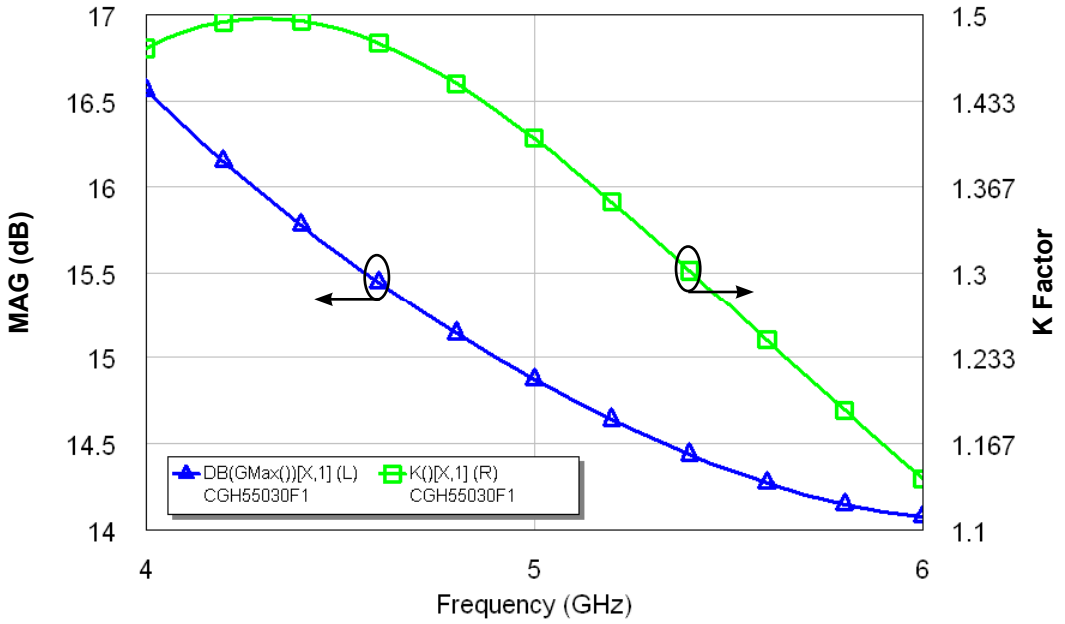
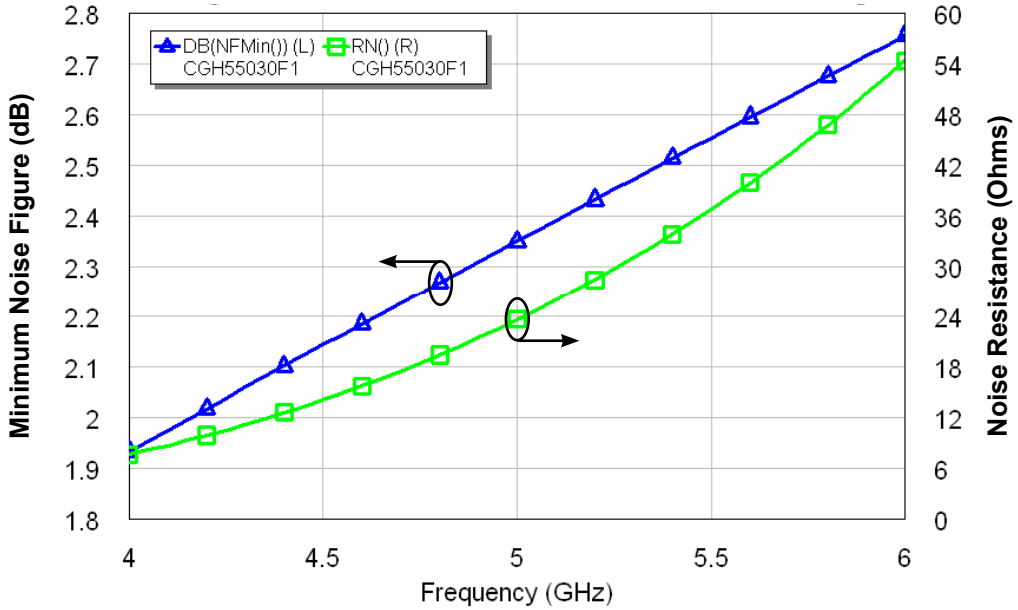
Typical Performance

Simulated Maximum Available Gain and K Factor of the CGH55030F1/P1
V_{DD} = 28 V, I_{DQ} = 250 mA



Typical Noise Performance

Simulated Minimum Noise Figure and Noise Resistance vs Frequency of the CGH55030F1/P1
V_{DD} = 28 V, I_{DQ} = 250 mA



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4600 Silicon Drive
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USA Tel: +1.919.313.5300
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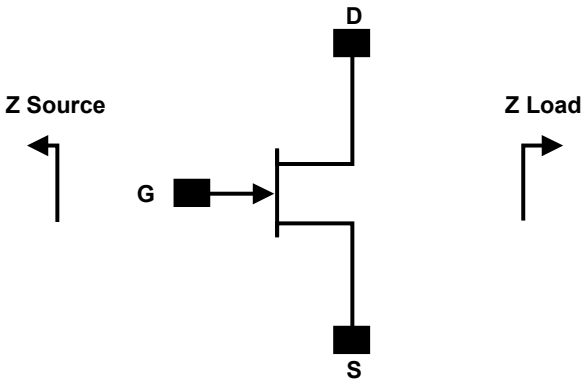
Source and Load Impedances



Frequency (MHz)	Z Source	Z Load
5500	8.0 – j12.4	14.1 – j12.6
5650	8.7 - j13.1	14.7 – j11.7
5800	8.4 - j14.0	15.4 – j11.0

Note 1. V_{DD} = 28V, I_{DQ} = 250 mA in the 440166 package.
Note 2. Impedances are extracted from the CGH55030-AMP demonstration amplifier and are not source and load pull data derived from the transistor.

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Test Methodology
Human Body Model	HBM	1A (> 250 V)	JEDEC JESD22 A114-D
Charge Device Model	CDM	II (200 < 500 V)	JEDEC JESD22 C101-C

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Durham, North Carolina, USA 27703
USA Tel: +1.919.313.5300
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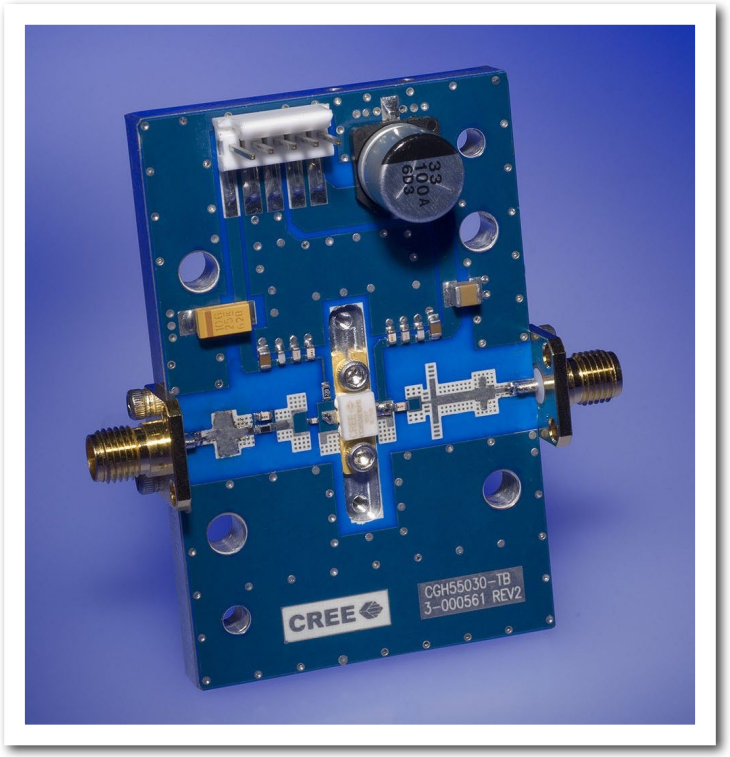
CGH55030-AMP Demonstration Amplifier Circuit Bill of Materials

Designator	Description	Qty
R1	RES, 1/16W, 0603, 1%, 562 OHMS	1
R2	RES, 1/16W, 0603, 1%, 22.6 OHMS	1
C2	CAP, 0.3pF, +/-0.05pF, 0402, ATC600L	1
C16	CAP, 33 UF, 20%, G CASE	1
C15	CAP, 1.0UF, 100V, 10%, X7R, 1210	1
C8	CAP 10UF 16V TANTALUM	1
C9	CAP, 0.4pF, +/-0.05pF, 0603, ATC600S	1
C1	CAP, 1.2pF, +/-0.1pF, 0603, ATC600S	1
C6,C13	CAP,200 PF,0603 PKG, 100 V	2
C4,C11	CAP, 10.0pF,+/-5%, 0603, ATC600S	2
C5,C12	CAP, 39pF, +/-5%, 0603, ATC600S	2
C7,C14	CAP, 330000PF, 0805, 100V, TEMP STABILIZ	2
J3,J4	CONN, SMA, PANEL MOUNT JACK, FLANGE	2
J1	HEADER RT>PLZ .1CEN LK 5POS	1
-	PCB, RO4350B, Er = 3.48, h = 20 mil	1
-	CGH55030	1

CGH55030-AMP Demonstration Amplifier Circuit



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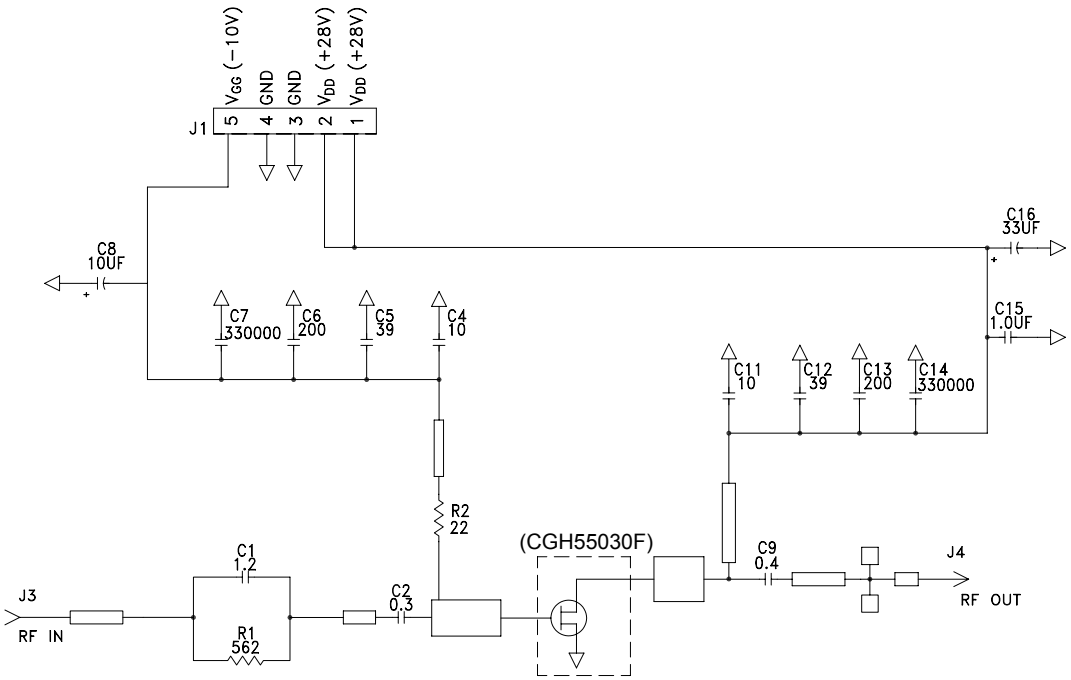
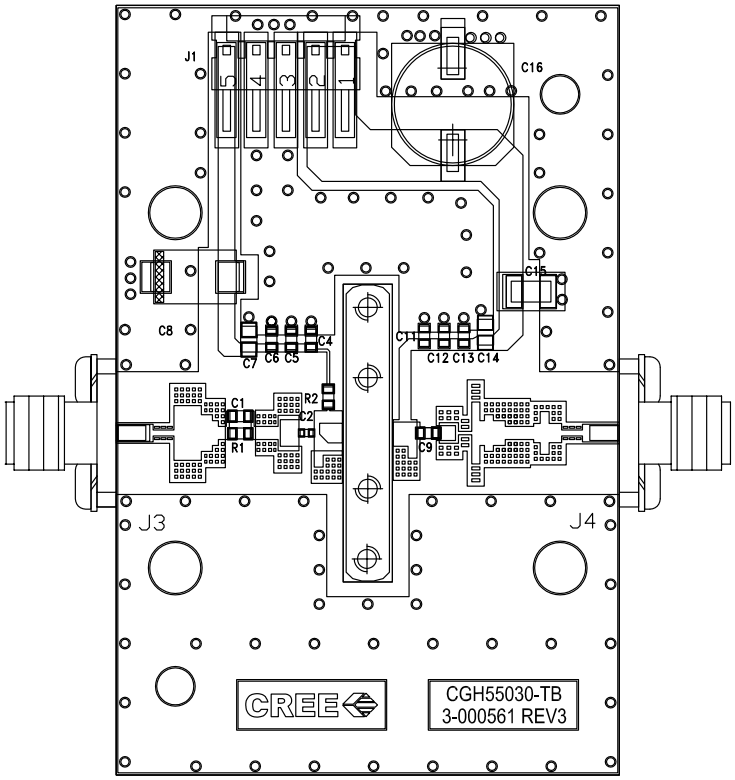
CGH55030-AMP Demonstration Amplifier Circuit Schematic



CGH55030-AMP Demonstration Amplifier Circuit Outline



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USA Tel: +1.919.313.5300
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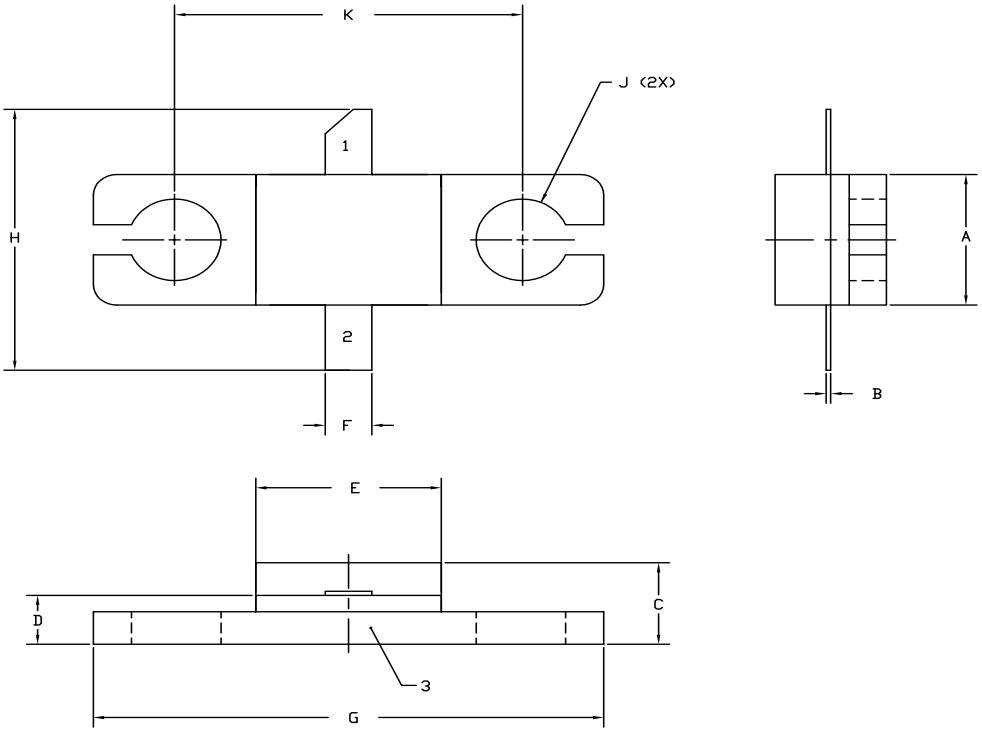
Typical Package S-Parameters for CGH55030F1 and CGH55030P1
(Small Signal, V_{DS} = 28 V, I_{DQ} = 250 mA, angle in degrees)

Frequency	Mag S11	Ang S11	Mag S21	Ang S21	Mag S12	Ang S12	Mag S22	Ang S22
500 MHz	0.917	-157.22	12.62	91.45	0.018	7.56	0.458	-158.97
600 MHz	0.916	-161.92	10.57	87.33	0.018	4.70	0.465	-160.93
700 MHz	0.916	-165.46	9.07	83.78	0.018	2.41	0.472	-162.19
800 MHz	0.916	-168.28	7.94	80.58	0.018	0.51	0.478	-163.04
900 MHz	0.916	-170.61	7.05	77.64	0.017	-1.12	0.485	-163.64
1.0 GHz	0.916	-172.60	6.33	74.88	0.017	-2.55	0.493	-164.09
1.2 GHz	0.917	-175.88	5.24	69.73	0.017	-4.94	0.508	-164.77
1.4 GHz	0.918	-178.57	4.46	64.94	0.017	-6.84	0.525	-165.36
1.6 GHz	0.919	179.09	3.87	60.41	0.016	-8.31	0.542	-165.99
1.8 GHz	0.921	176.98	3.40	56.07	0.016	-9.39	0.559	-166.73
2.0 GHz	0.922	175.03	3.03	51.90	0.015	-10.06	0.577	-167.59
2.2 GHz	0.924	173.17	2.73	47.87	0.014	-10.31	0.594	-168.57
2.4 GHz	0.925	171.39	2.47	43.97	0.014	-10.12	0.610	-169.67
2.6 GHz	0.926	169.65	2.26	40.19	0.013	-9.46	0.626	-170.88
2.8 GHz	0.928	167.93	2.08	36.52	0.013	-8.31	0.642	-172.17
3.0 GHz	0.929	166.24	1.92	32.94	0.013	-6.65	0.656	-173.55
3.2 GHz	0.930	164.54	1.78	29.45	0.012	-4.49	0.670	-175.00
3.4 GHz	0.931	162.85	1.66	26.05	0.012	-1.85	0.683	-176.50
3.6 GHz	0.932	161.14	1.55	22.72	0.012	1.19	0.695	-178.06
3.8 GHz	0.933	159.42	1.46	19.46	0.012	4.55	0.706	-179.66
4.0 GHz	0.933	157.68	1.38	16.27	0.012	8.08	0.716	178.70
4.1 GHz	0.934	156.80	1.34	14.69	0.012	9.87	0.721	177.86
4.2 GHz	0.934	155.91	1.31	13.12	0.012	11.64	0.726	177.02
4.3 GHz	0.934	155.01	1.27	11.57	0.012	13.38	0.730	176.17
4.4 GHz	0.934	154.11	1.24	10.03	0.013	15.08	0.735	175.30
4.5 GHz	0.935	153.20	1.21	8.49	0.013	16.71	0.739	174.44
4.6 GHz	0.935	152.28	1.18	6.97	0.013	18.26	0.743	173.56
4.7 GHz	0.935	151.35	1.16	5.46	0.013	19.72	0.746	172.67
4.8 GHz	0.935	150.41	1.13	3.95	0.014	21.09	0.750	171.78
4.9 GHz	0.935	149.46	1.11	2.46	0.014	22.35	0.753	170.88
5.0 GHz	0.935	148.49	1.08	0.96	0.015	23.50	0.756	169.97
5.1 GHz	0.935	147.52	1.06	-0.52	0.015	24.55	0.760	169.05
5.2 GHz	0.935	146.53	1.04	-2.00	0.016	25.48	0.762	168.12
5.3 GHz	0.935	145.53	1.02	-3.48	0.016	26.30	0.765	167.18
5.4 GHz	0.935	144.52	1.00	-4.96	0.017	27.02	0.768	166.24
5.5 GHz	0.935	143.49	0.99	-6.43	0.018	27.62	0.770	165.28
5.6 GHz	0.935	142.45	0.97	-7.90	0.018	28.12	0.773	164.32
5.7 GHz	0.934	141.39	0.95	-9.37	0.019	28.53	0.775	163.35
5.8 GHz	0.934	140.31	0.94	-10.84	0.020	28.83	0.777	162.36
5.9 GHz	0.934	139.22	0.93	-12.32	0.020	29.05	0.779	161.37
6.0 GHz	0.934	138.12	0.91	-13.79	0.021	29.18	0.781	160.36

To download the s-parameters in s2p format, go to the CGH55030F1/P1 Product Page, click on the documentation tab.

Cree, Inc.
4600 Silicon Drive
Durham, North Carolina, USA 27703
USA Tel: +1.919.313.5300
Fax: +1.919.869.2733
www.cree.com/rf

Product Dimensions CGH55030F1 (Package Type — 440166)



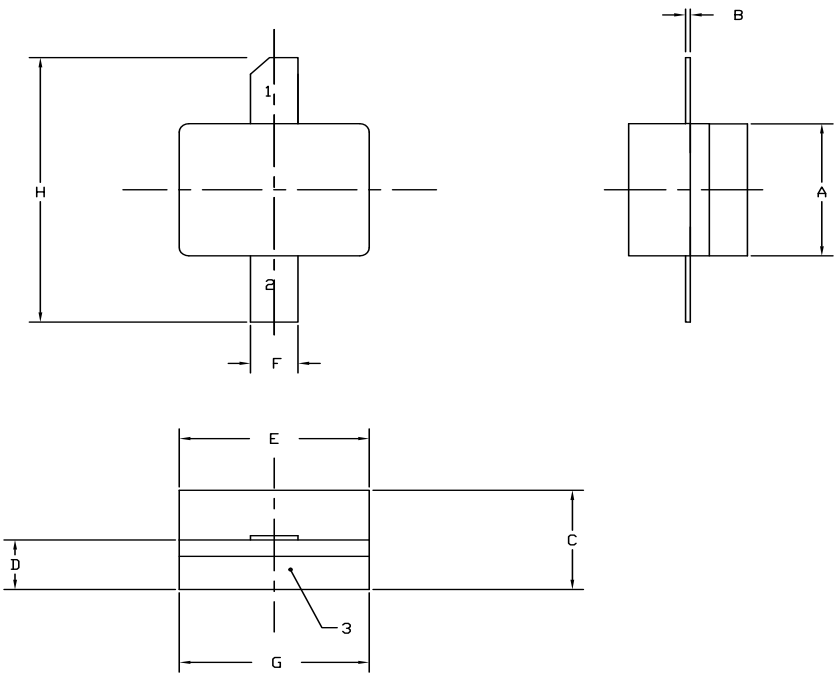
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE NI/AU

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.155	0.165	3.94	4.19
B	0.004	0.006	0.10	0.15
C	0.115	0.135	2.92	3.43
D	0.057	0.067	1.45	1.70
E	0.195	0.205	4.95	5.21
F	0.045	0.055	1.14	1.40
G	0.545	0.555	13.84	14.09
H	0.280	0.360	7.11	9.14
J	ø .100		2.54	
K	0.375		9.53	

PIN 1. GATE
PIN 2. DRAIN
PIN 3. SOURCE

Product Dimensions CGH55030P1 (Package Type — 440196)



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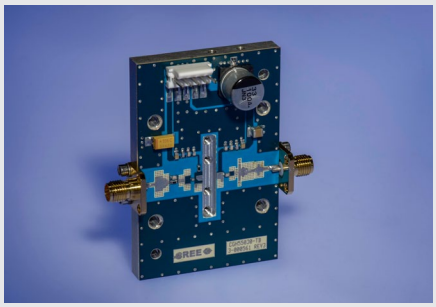
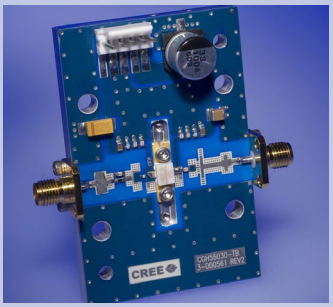
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE NI/AU

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.155	0.165	3.94	4.19
B	0.003	0.006	0.10	0.15
C	0.115	0.135	2.92	3.17
D	0.057	0.067	1.45	1.70
E	0.195	0.205	4.95	5.21
F	0.045	0.055	1.14	1.40
G	0.195	0.205	4.95	5.21
H	0.280	0.360	7.11	9.14

PIN 1. GATE
PIN 2. DRAIN
PIN 3. SOURCE

Cree, Inc.
4600 Silicon Drive
Durham, North Carolina, USA 27703
USA Tel: +1.919.313.5300
Fax: +1.919.869.2733
www.cree.com/rf

Product Ordering Information

Order Number	Description	Unit of Measure	Image
CGH55030F1	GaN HEMT	Each	2.709 inv
CGH55030P1	GaN HEMT	Each	4.584 in
CGH55030-TB	Test board without GaN HEMT	Each	
CGH55030-AMP	Test board with GaN HEMT installed	Each	

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For more information, please contact:

Cree, Inc.
4600 Silicon Drive
Durham, North Carolina, USA 27703
www.cree.com/RF

Sarah Miller
Marketing
Cree, RF Components
1.919.407.5302

Ryan Baker
Marketing & Sales
Cree, RF Components
1.919.407.7816

Tom Dekker
Sales Director
Cree, RF Components
1.919.407.5639

Cree, Inc.
4600 Silicon Drive
Durham, North Carolina, USA 27703
USA Tel: +1.919.313.5300
Fax: +1.919.869.2733
www.cree.com/rf